

Noval ultrafast gigahertz high-power semiconductor lasers: MIXSELs and SESAM modelocked VECSELs

T. Südmeyer, U. Keller

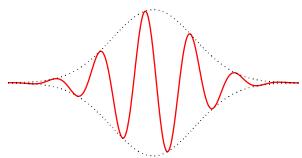
Department of Physics, Institute of Quantum Electronics,
ETH Zurich, Switzerland

28.10.2010, IBM Research - Zurich, Ruschlikon

Ultrafast lasers

... generate well-controlled flashes of light with pico- or femtosecond duration

Access ultrashort time scales

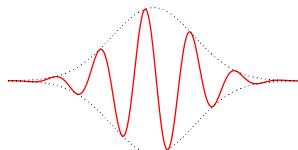


➡ Observe and use fast dynamics

Ultrafast lasers

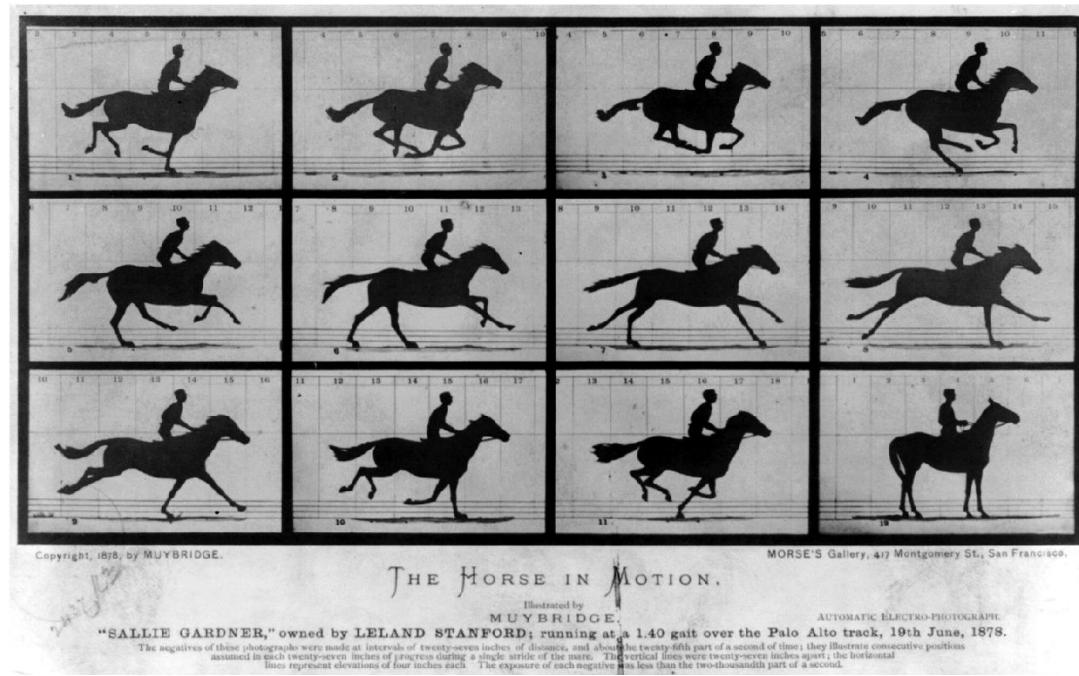
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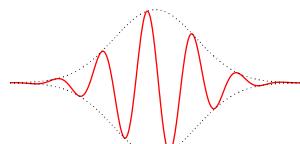
E. Muybridge in 1878:
understand horse gallop



Ultrafast lasers

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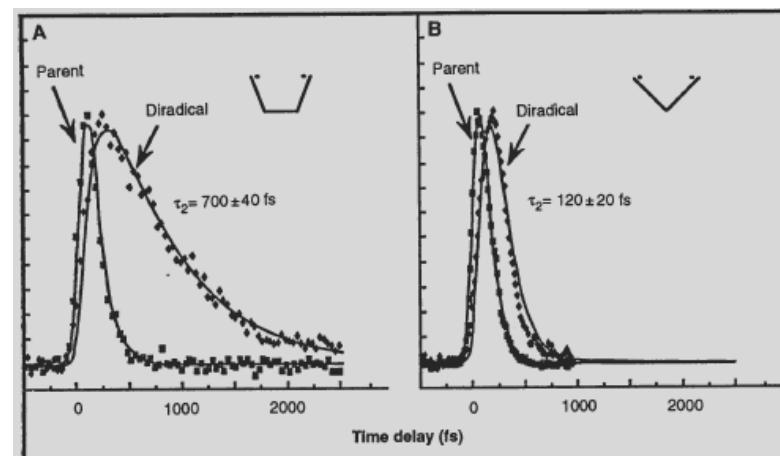
Access ultrashort time scales



➡ Observe and use fast dynamics

E. Muybridge in 1878:
understand horse gallop

A. H. Zewail in 1994:
understand transition states in
chemical reactions

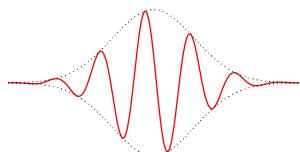


SCIENCE • VOL. 266 • 25 NOVEMBER 1994

Ultrafast lasers

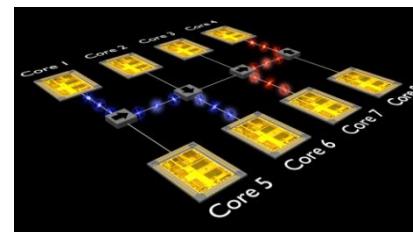
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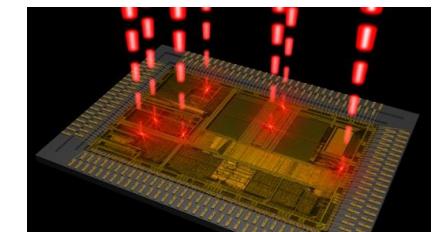


Observe and use fast dynamics

- understand chemical reaction dynamics
- fast communication
- ...



interconnects

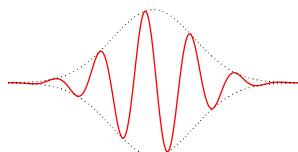


optical clocking

Ultrafast lasers

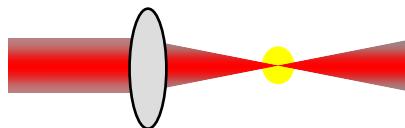
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Access ultrashort time scales



- ⇒ Observe and use fast dynamics
- understand chemical reaction dynamics
 - fast communication
 - ...

Concentrate in time and space



- ⇒ Achieve extremely high intensities
- material processing
 - multi-photon biomedical imaging
 - ...

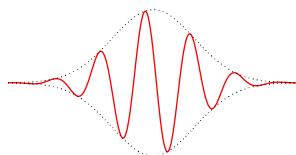


2-photon image of
muscle tissue

Ultrafast lasers

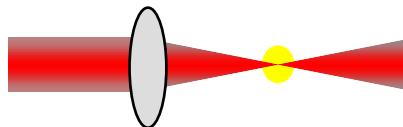
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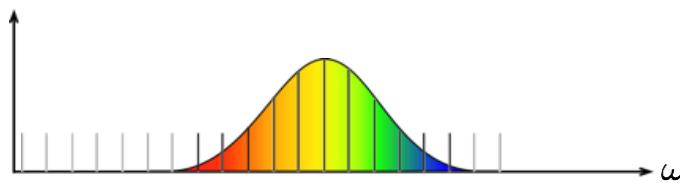
- ⇒ Observe and use fast dynamics
- understand chemical reaction dynamics
 - fast communication
 - ...

Concentrate in time and space



- ⇒ Achieve extremely high intensities
- material processing
 - multi-photon biomedical imaging
 - ...

Broad optical spectrum



- ⇒ Generate ultrastable frequency combs
- high precision spectroscopy
 - optical clocks
 - ...

Ultrafast semiconductor lasers

- Currently, typical ultrafast lasers are bulky and complex



~ 100 cm

Ultrafast semiconductor lasers

- Currently, typical ultrafast lasers are bulky and complex



- Our approach: semiconductor laser with vertical integration



VECSEL

Vertical External
Cavity Surface
Emitting Laser

SESAM

Semiconductor
Saturable Absorber
Mirror

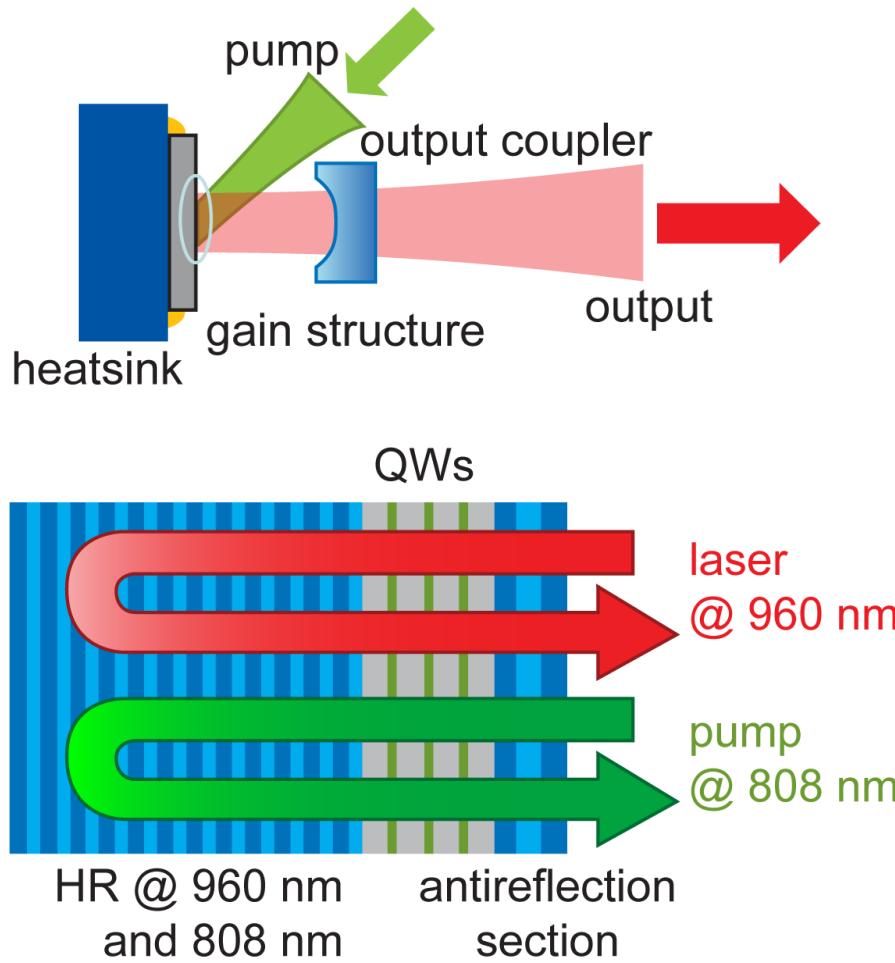
MIXSEL

Modelocked Integrated
External-Cavity Surface
Emitting Laser

Outline

1. Introduction and Motivation
2. High power cw VECSELs
3. Modelocked VECSELs
4. MIXSELs
5. Electrically pumped VECSELs and MIXSELs
6. Summary and outlook

Combine the advantages of **ion-doped DPSSL** and **semiconductor lasers**



M. Kuznetsov et al., *IEEE Phot. Tech. Lett.* **9**, 1063 (1997)

Surface Emitter

- Power scalability

Optical Pumping

- Large area homogeneous inversion

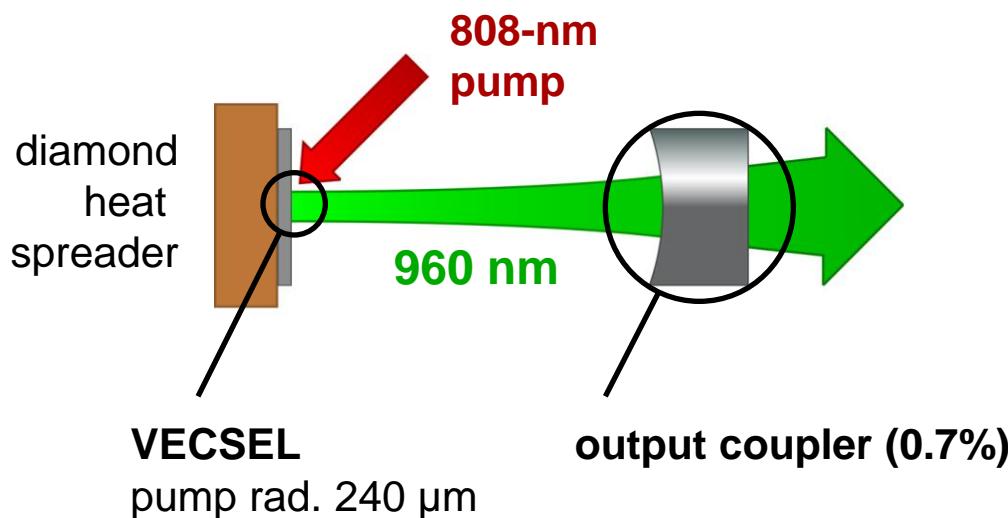
External cavity

- Excellent beam quality
- flexible: SHG, modelocking single-frequency

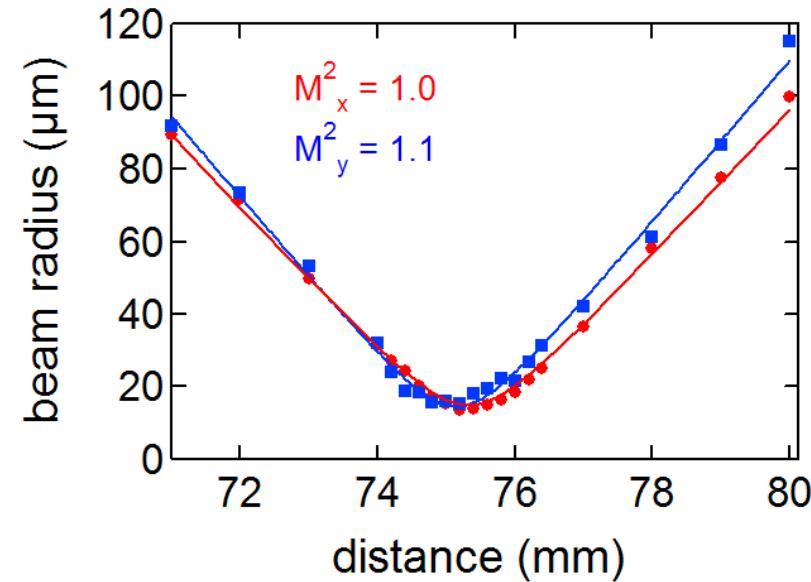
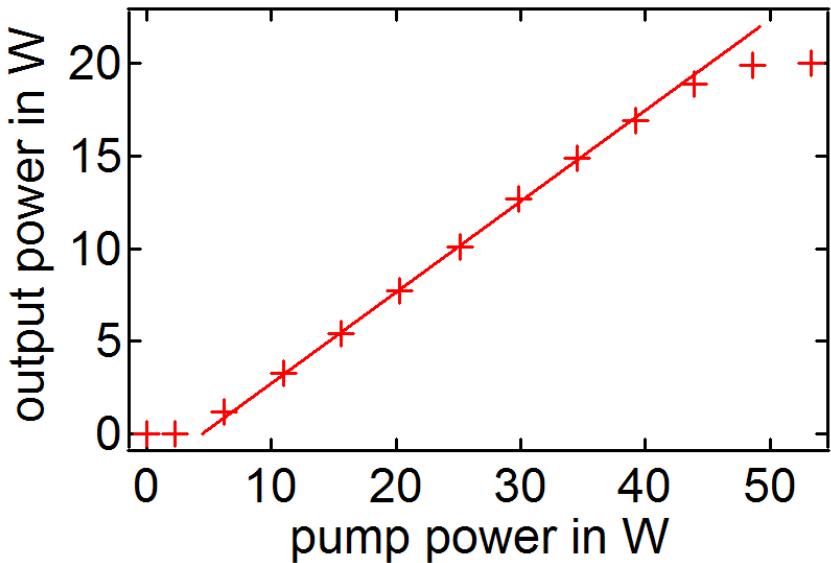
Semiconductor Gain

- bandgap engineering: so far 0.6 ... 2.3 μm
- cost-efficient fabrication

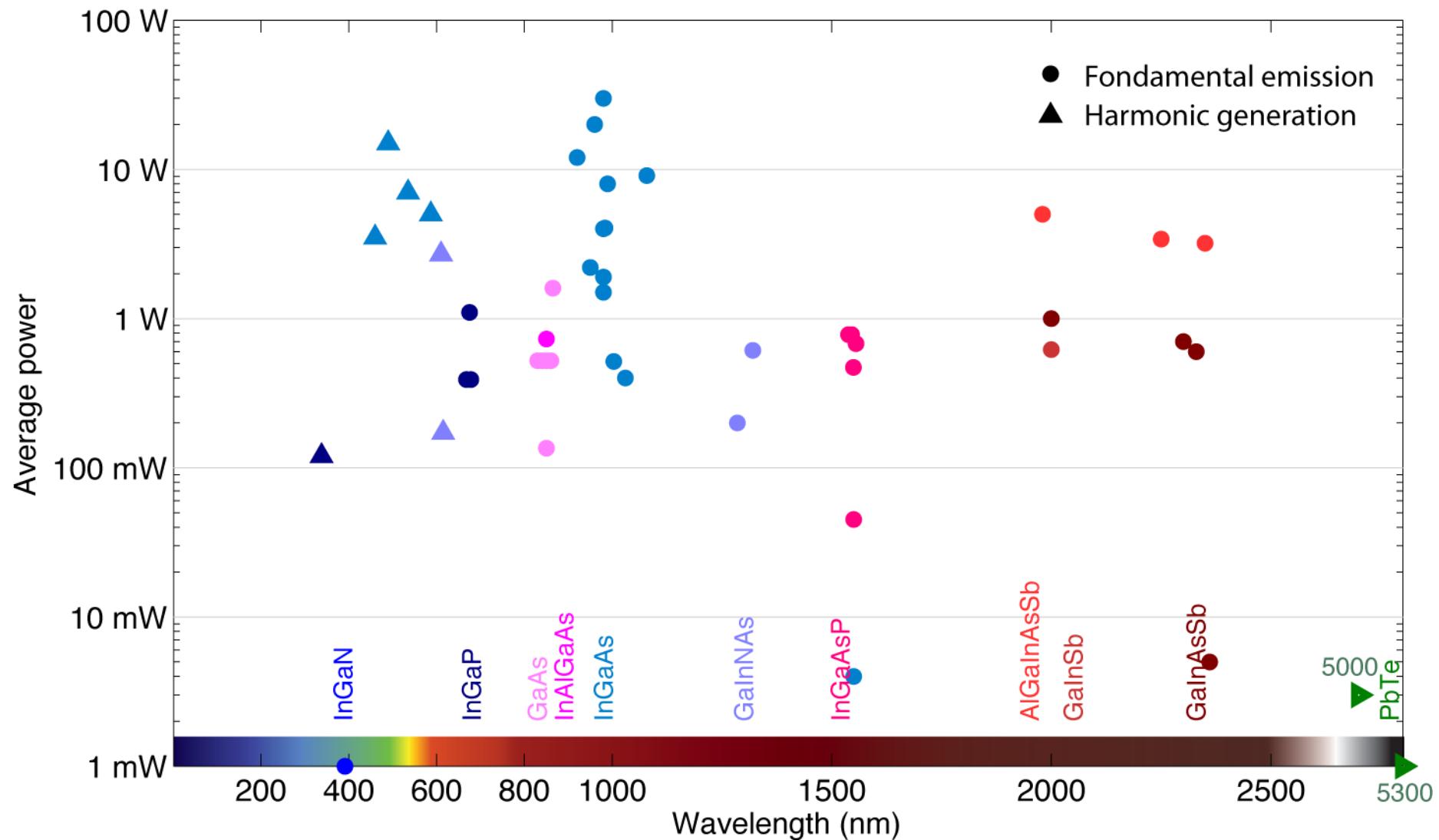
High power CW-operation: 20 W TEM₀₀



- Maximum power $P = 20.2 \text{ W}$
- Up to $\eta_{\text{opt-opt}} = 43\%$
- $M^2 < 1.1$



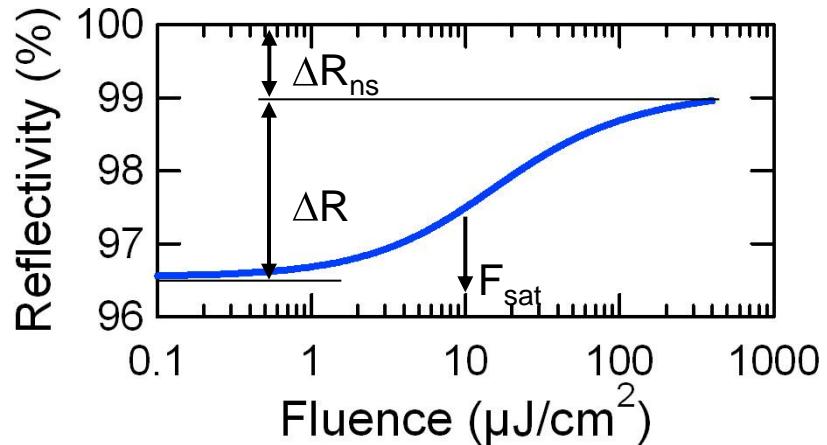
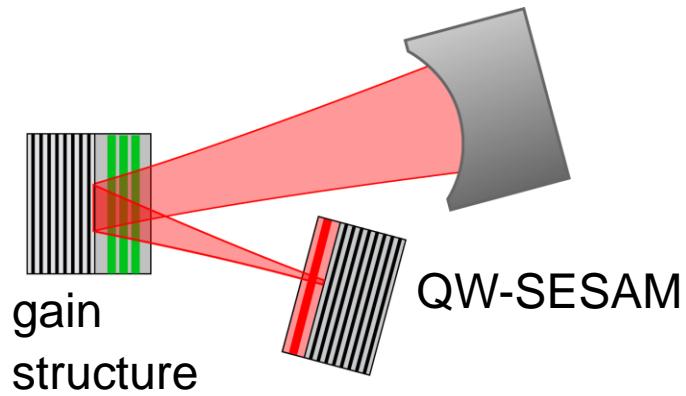
Bandgap engineering



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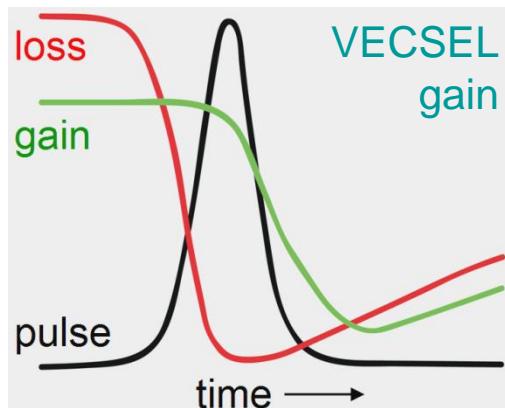
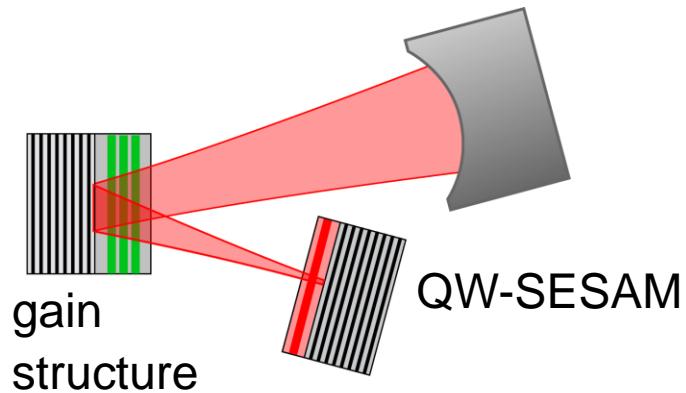
SESAM-VECSEL modelocking



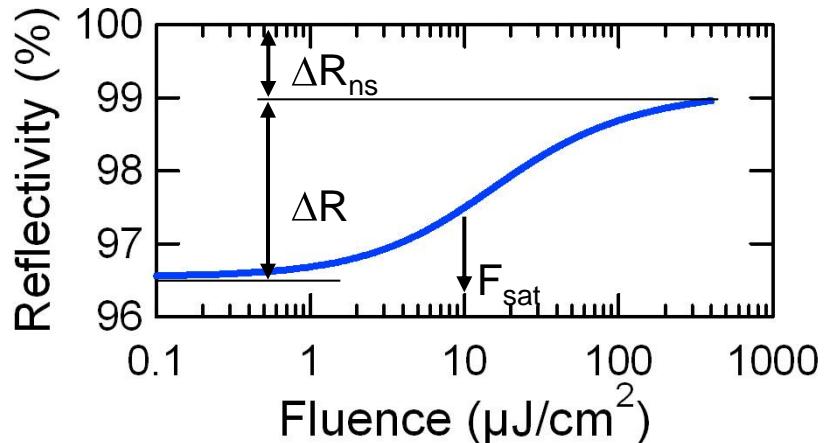
- Self-starting and reliable modelocking
- After each roundtrip a pulse is emitted
 - 1 GHz: $T_{\text{roundtrip}} = 1 \text{ ns}$, $L_{\text{cavity}} = 15 \text{ cm}$
 - 50 GHz: $T_{\text{roundtrip}} = 20 \text{ ps}$, $L_{\text{cavity}} = 3 \text{ mm}$

#1 U. Keller et al., *Opt. Lett.* **17**, 505, 1992#2 U. Keller, *Nature* **424**, 831, 2003

SESAM-VECSEL modelocking



⇒ loss has to saturate faster



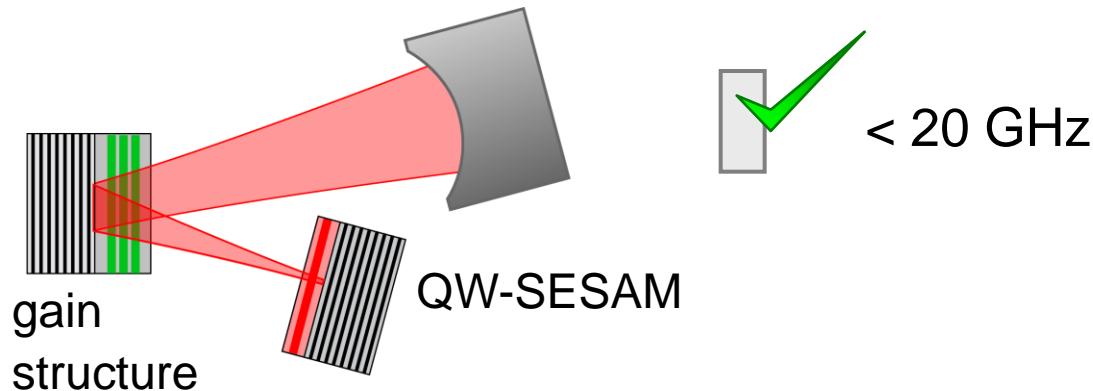
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$$\frac{E_{sat,a}}{E_{sat,g}} = \frac{F_{sat,a}}{F_{sat,g}} \frac{A_g}{A_a} < 1$$

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SESAM-VECSEL modelocking



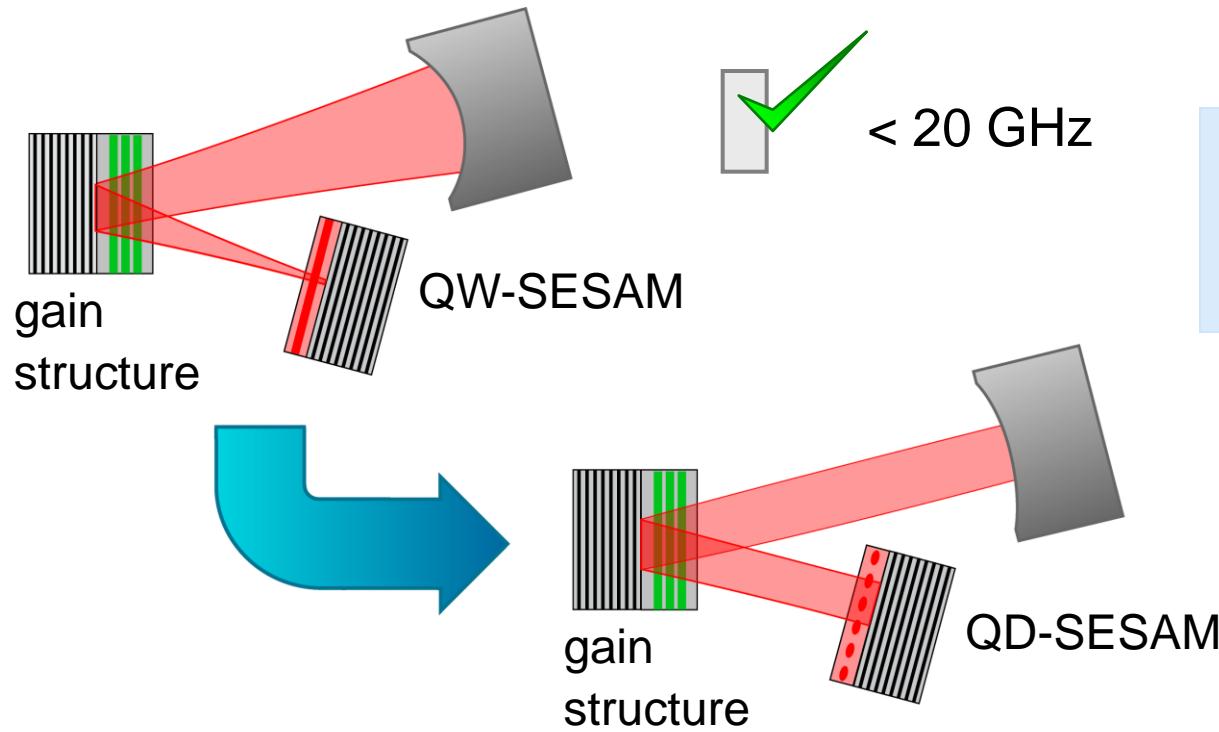
Quantum-Well SESAM ML

4 GHz	2.1 W	4.7 ps
10 GHz	1.4 W	6.1 ps

$$\frac{E_{sat,a}}{E_{sat,g}} = \frac{F_{sat,a}}{F_{sat,g}} \frac{A_a}{A_g} < 1$$

typically 1/4 – 1/20
for QW-SESAMs

SESAM-VECSEL modelocking



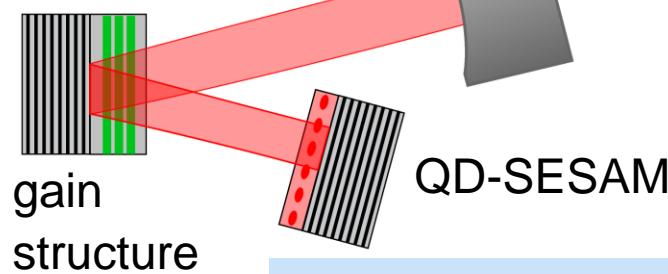
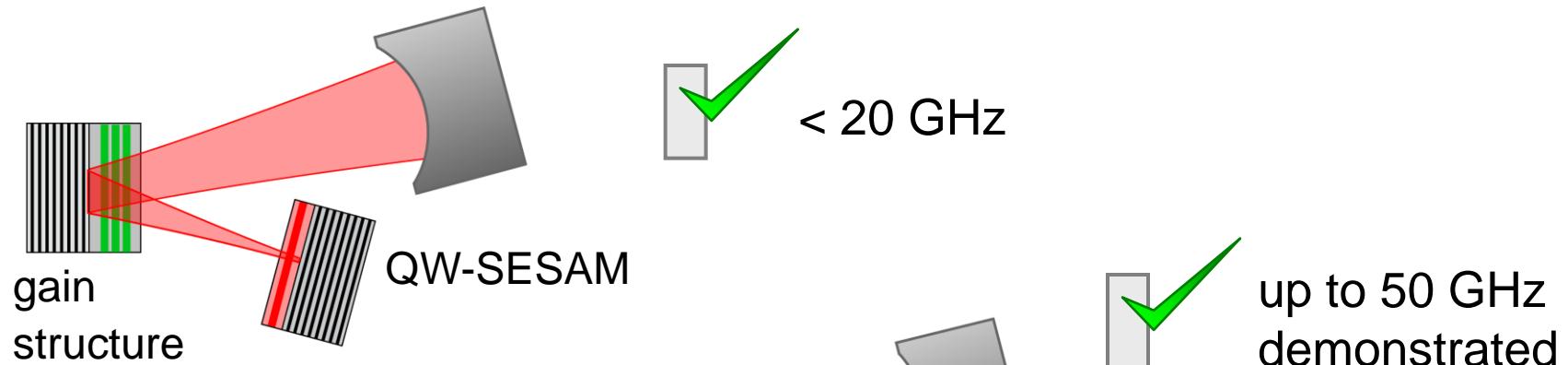
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4 GHz	2.1 W	4.7 ps
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$$\frac{E_{sat,a}}{E_{sat,g}} = \left(\frac{F_{sat,a}}{F_{sat,g}} \right) \frac{A_a}{A_g} < 1$$

With lower saturation fluence
⇒ no focusing needed anymore!

SESAM-VECSEL modelocking

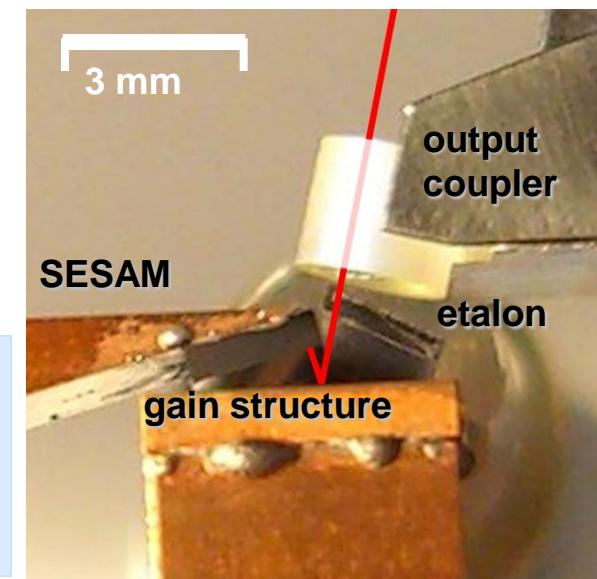
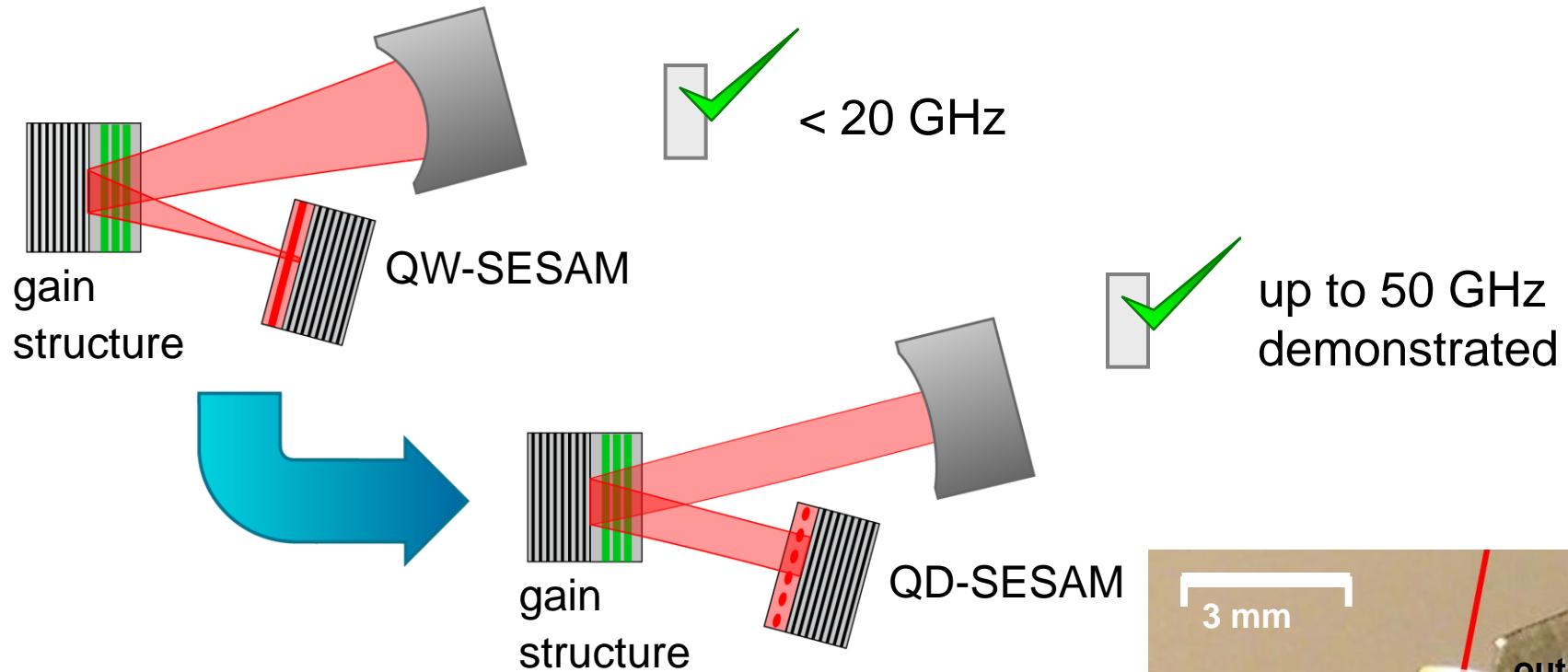


Quantum-Dot SESAM

- modulation depth ΔR & F_{sat} decoupled
- resonant design to decrease F_{sat}
- low-T growth for fast recovery

$\Rightarrow \sim 10\text{-fold } F_{\text{sat}} \text{ reduction}$

SESAM-VECSEL modelocking

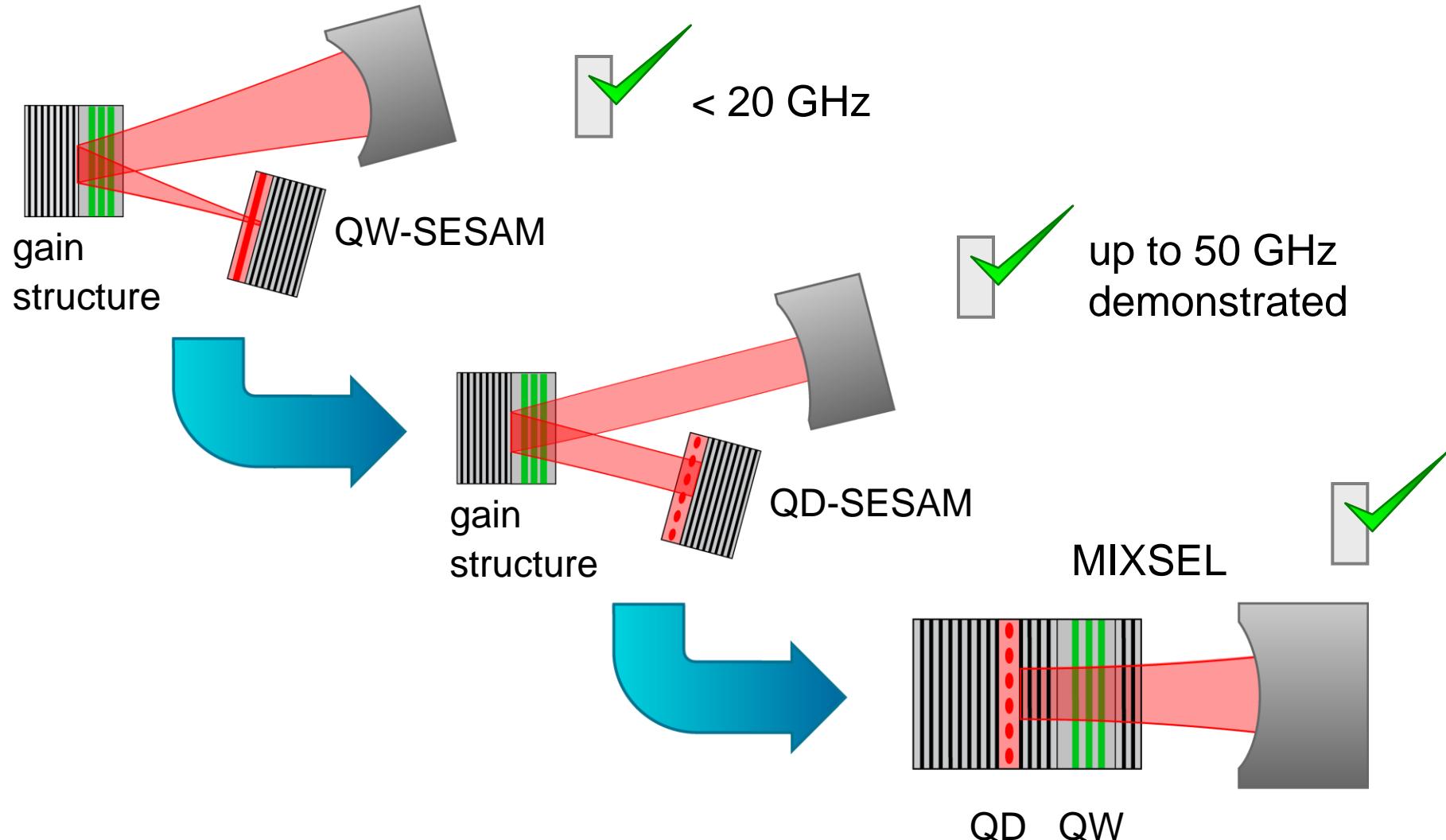


QD-SESAM modelocking: up to 50 GHz repetition rate

D. Lorenser et al., IEEE J. Quantum Electron., vol. 42, pp. 838-847, 2006.

- 102 mW average power, center wavelength 958.5 nm
- 3.3 ps pulse duration

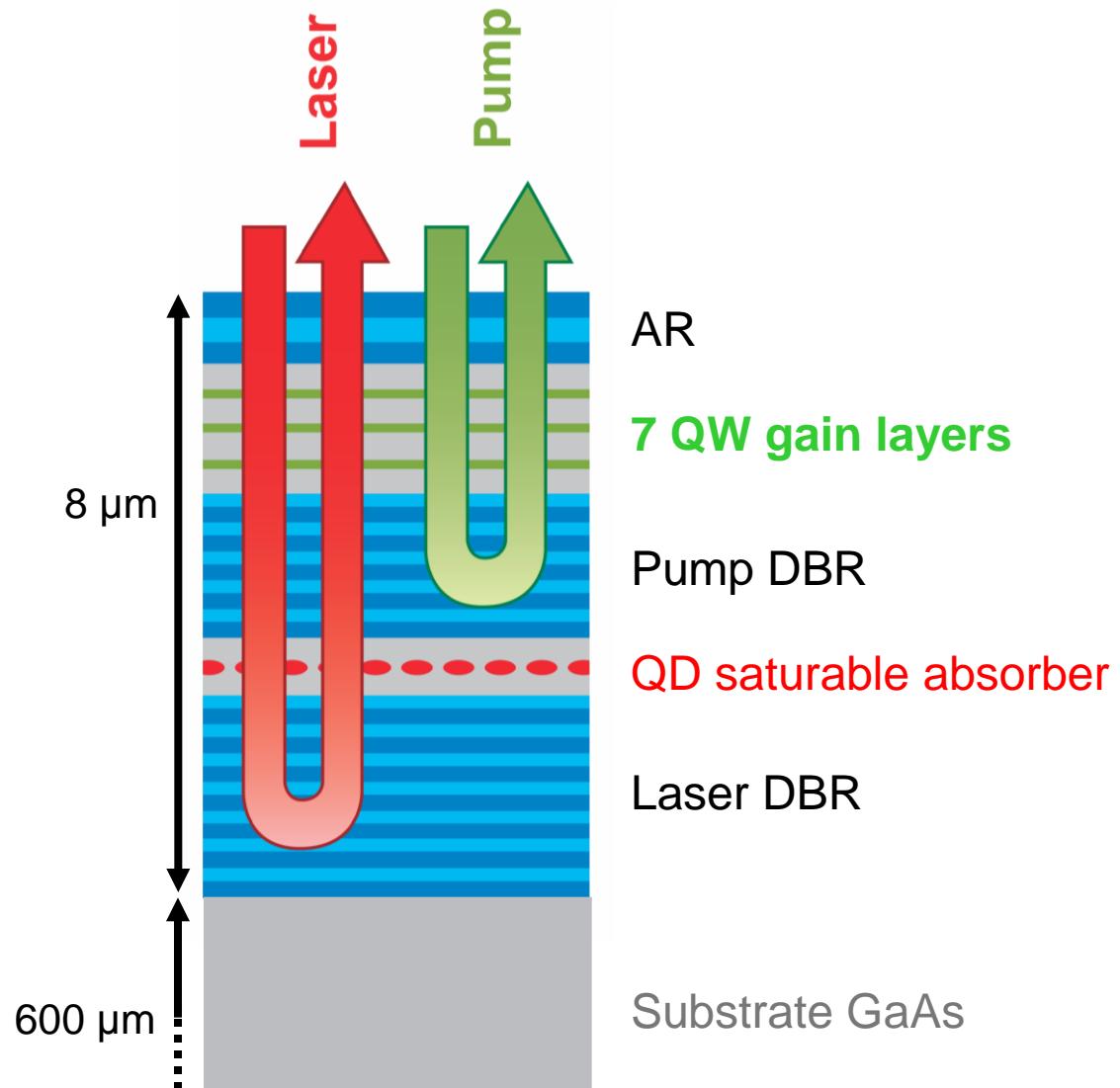
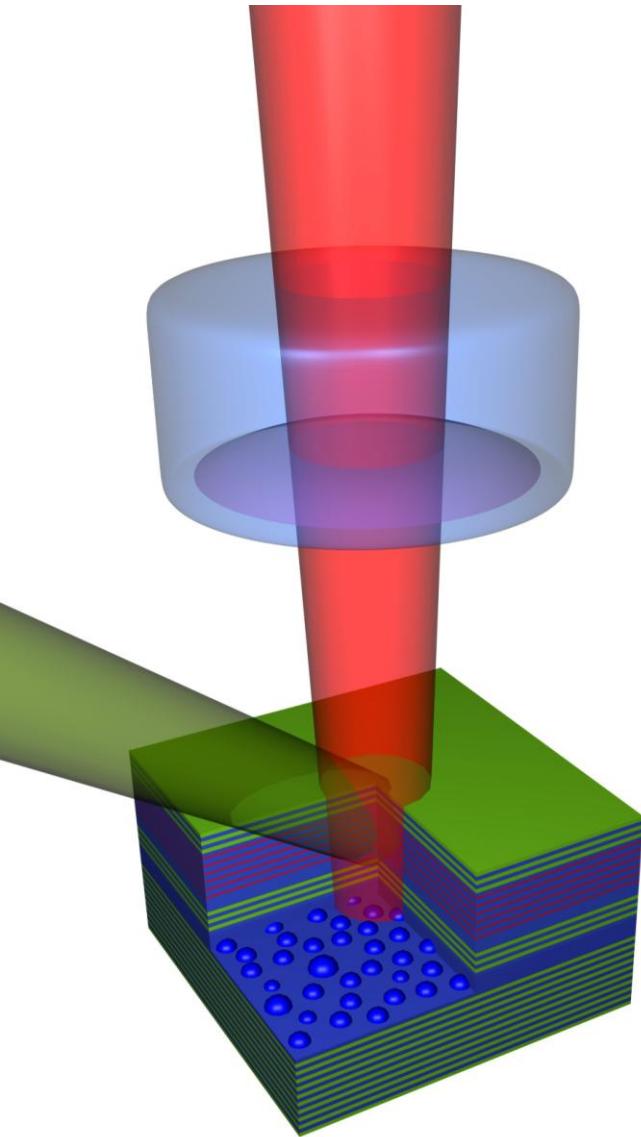
SESAM-VECSEL modelocking



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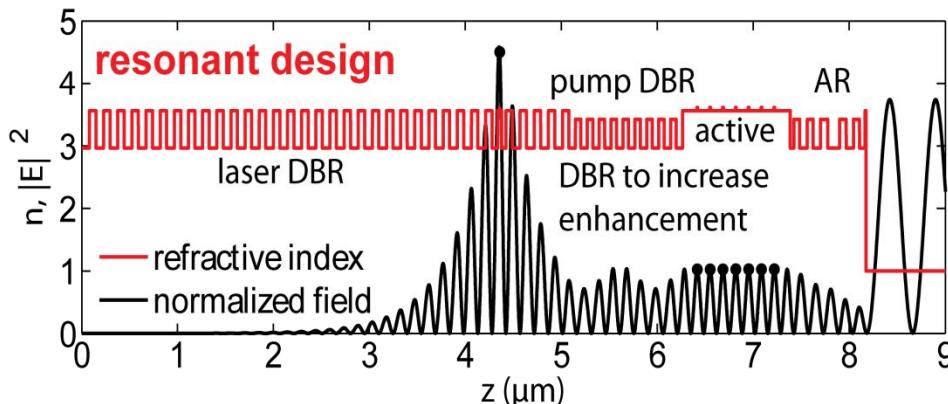
MIXSEL concept



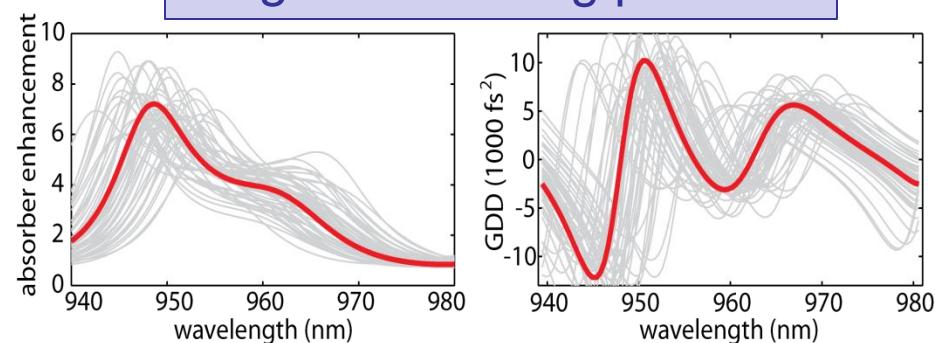
Resonant vs. antiresonant design

Initial MIXSEL demonstration had a **resonant design**:

D. J. H. C. Maas et al., *Appl. Phys. B* **88**, 493, 2007



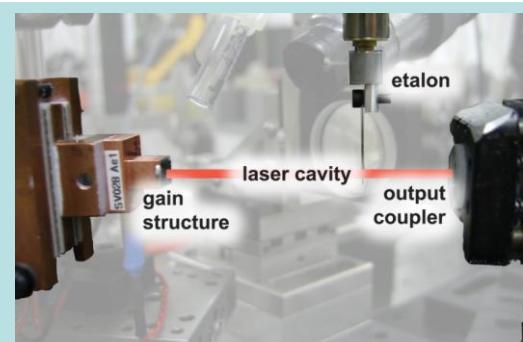
- sensitive to growth errors
- high GDD - long pulses



growth error simulation:
layer thickness variations < 1%

- Field enhancement in QD-layer by resonant sub-cavity
 - low saturation fluence $< 10 \text{ } \mu\text{J}/\text{cm}^2$

pulse repetition rate:	2.8 GHz
average output power:	185 mW
pulse duration:	32 ps
heat sink temperature:	-50°C

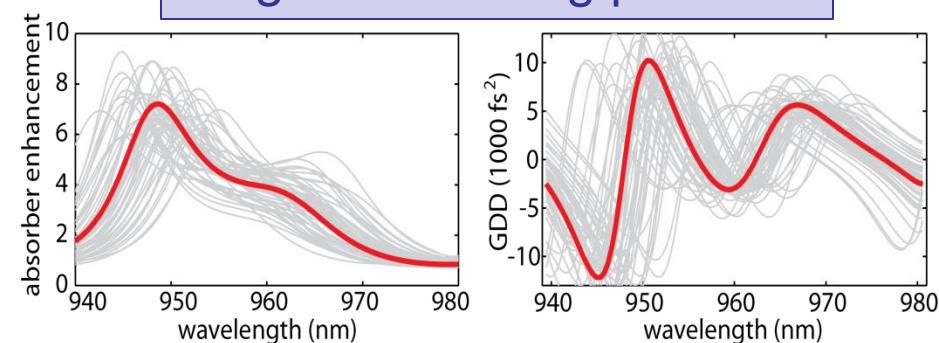
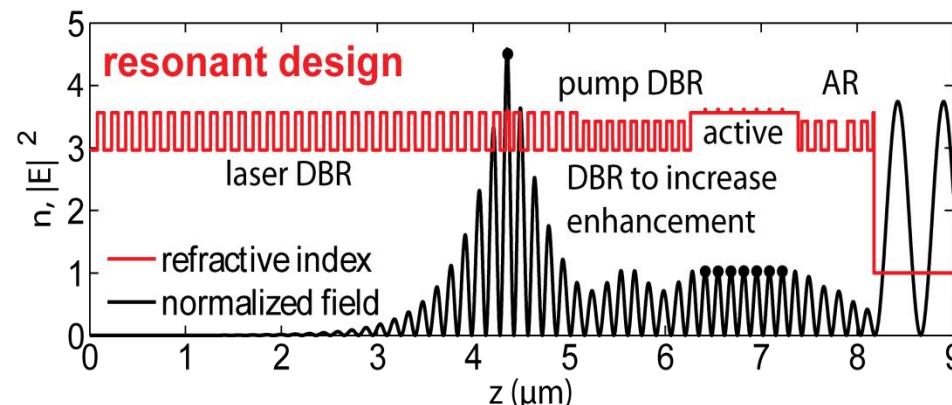


Resonant vs. antiresonant design

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D. J. H. C. Maas et al., *Appl. Phys. B* **88**, 493, 2007

- sensitive to growth errors
- high GDD - long pulses



- Field enhancement in QD-layer by resonant sub-cavity
 - low saturation fluence $< 10 \mu\text{J}/\text{cm}^2$
- Recently: detailed study on QD-growth parameters
 - optimization of growth temperature and post-growth annealing
 - achieved first 1:1 SESAM-VECSEL modelocking from antiresonant SESAM

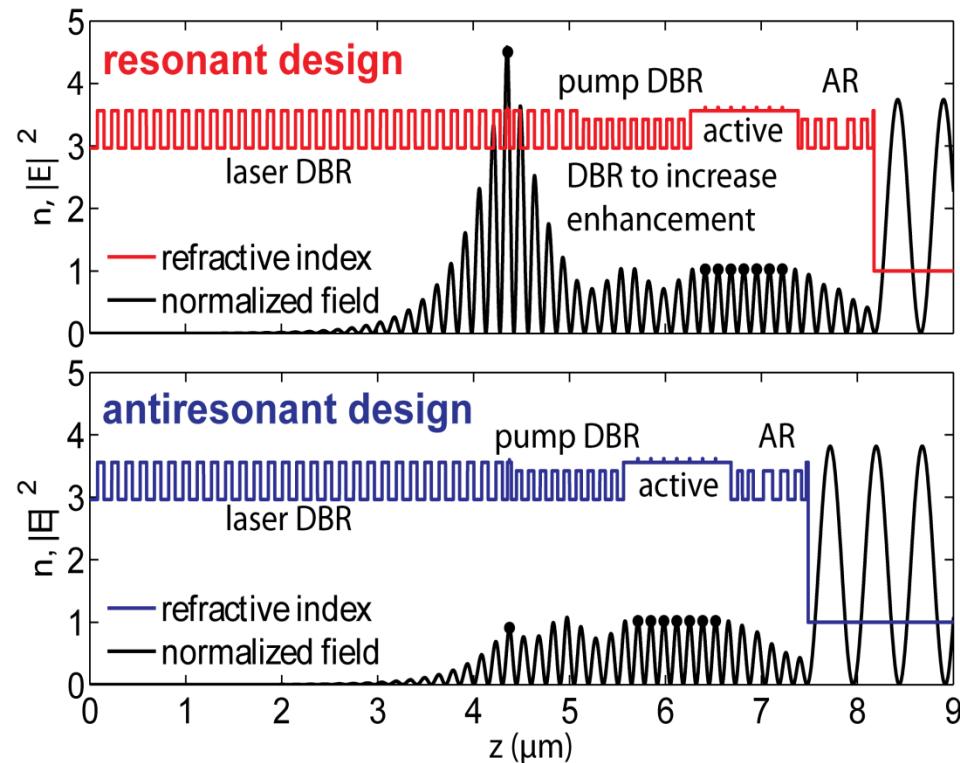
growth error simulation:
layer thickness variations $< 1\%$

A.-R. Bellancourt, Y. Barbarin, D. J. H. C. Maas, M. Shafiei, M. Hoffmann, M. Golling, T. Südmeyer and U. Keller, *OE*, 17, 12, 9704 (2009)
D. J. H. C. Maas, A. R. Bellancourt, M. Hoffmann, B. Rudin, Y. Barbarin, M. Golling, T. Südmeyer and U. Keller, *OE*, 16, 23, 18646 (2008)

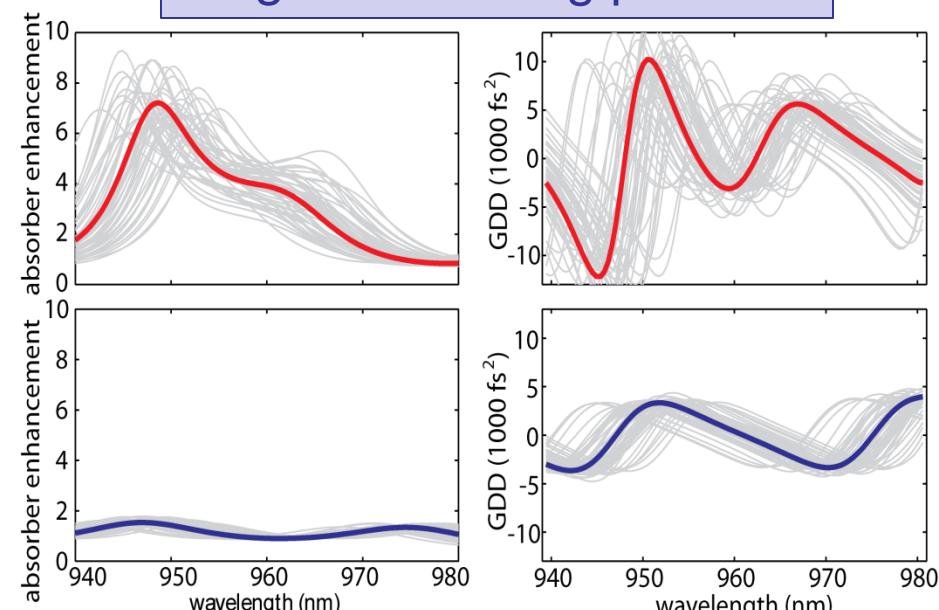
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- sensitive to growth errors
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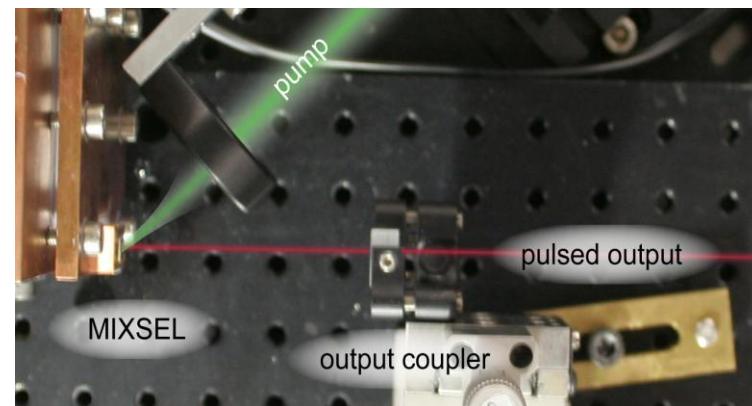
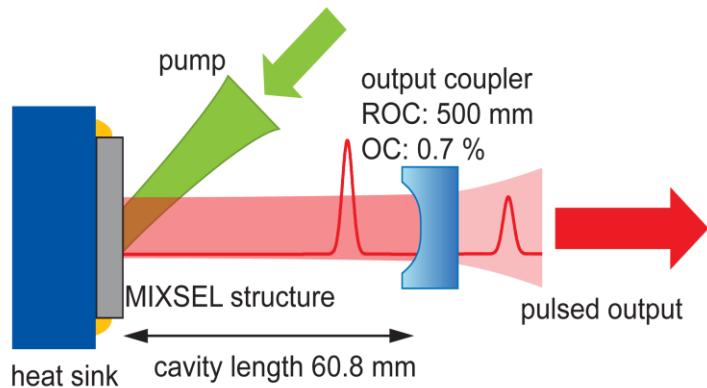
growth error simulation:
layer thickness variations < 1%

New: MIXSEL demonstration
with **antiresonant design**

- tolerant to growth errors
- low GDD - short pulses

MIXSEL on diamond heat sink

- First MIXSEL with diamond heat sink instead of GaAs wafer
- Increase pump spot from 80 µm radius to ~215 µm
- Achieve new power record: 6.4 W in 28 ps at 2.5 GHz



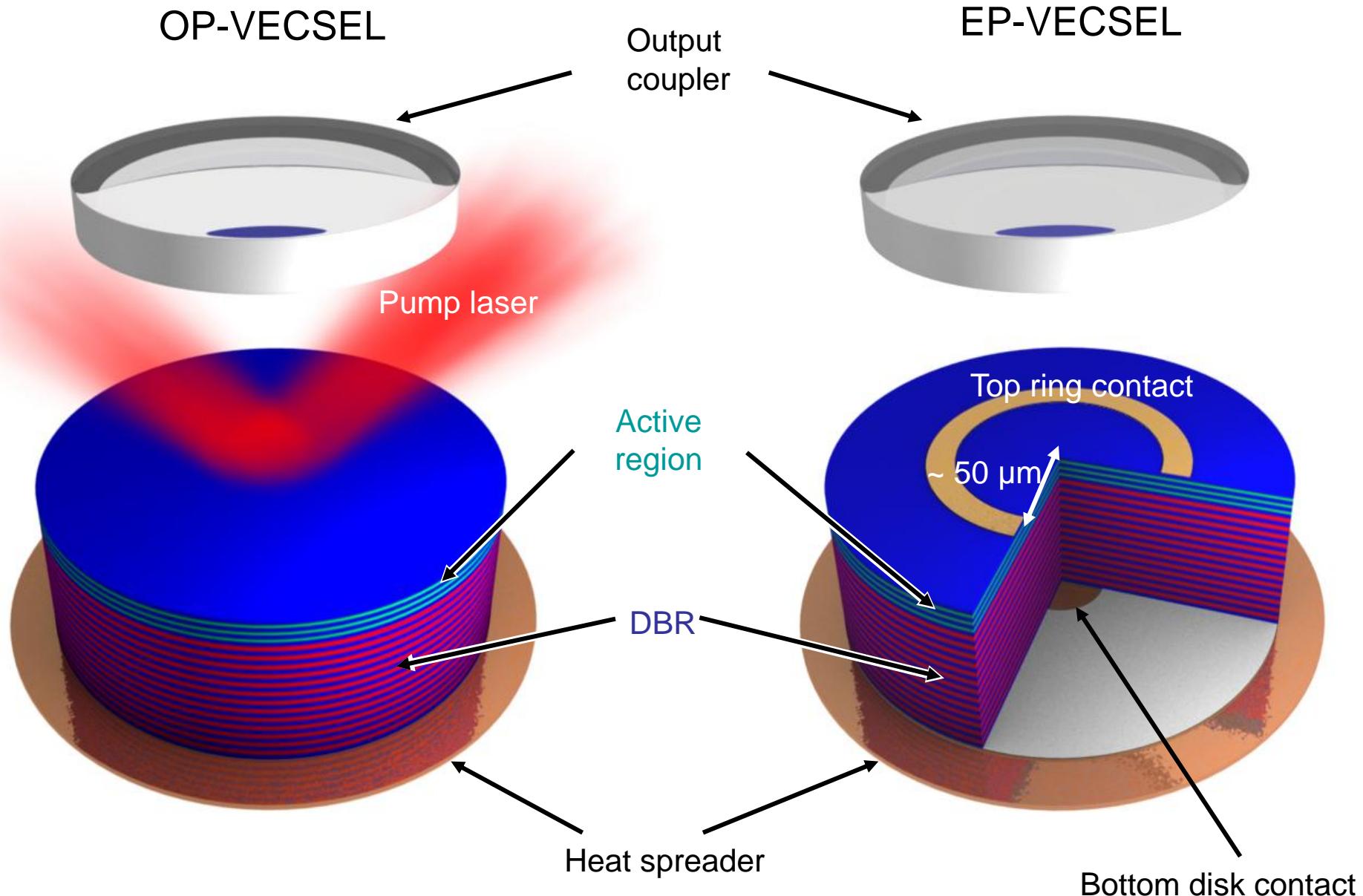
average output power: 6.4 W
pulse duration: 28.1 ps
center wavelength: 959.1 nm
FWHM spectral width: 0.15 nm
optical pumping 36.7 W at 808 nm

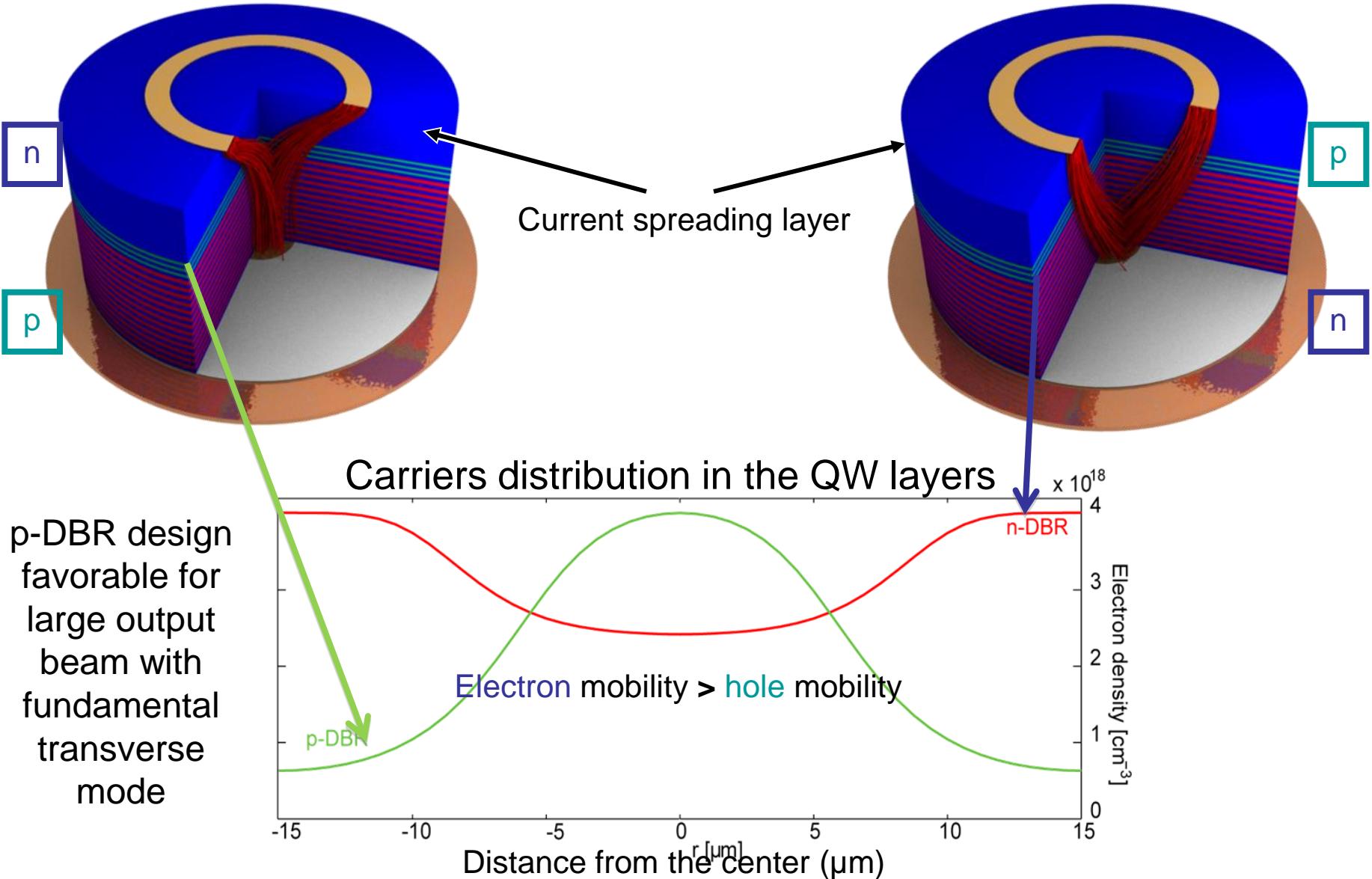
pump / laser spot radius: ~215 µm
TBP: 1.35 (4.2 times sech²)
efficiency (opt-opt): 17.4 %

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Electrical vs. optical pumping

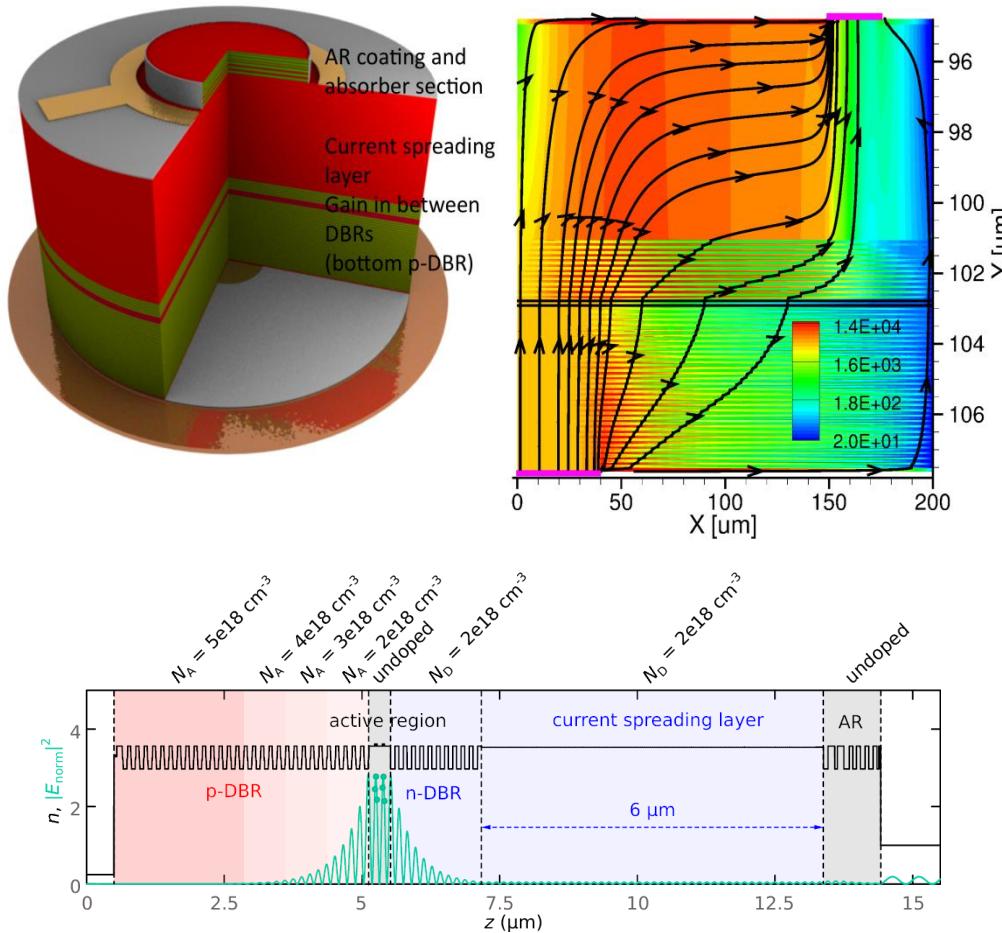




P. Kreuter et al., *Appl. Phys. B*, **91**, 257, 2008

EP-VECSEL: some design features

Trade off between optical losses and electrical resistance

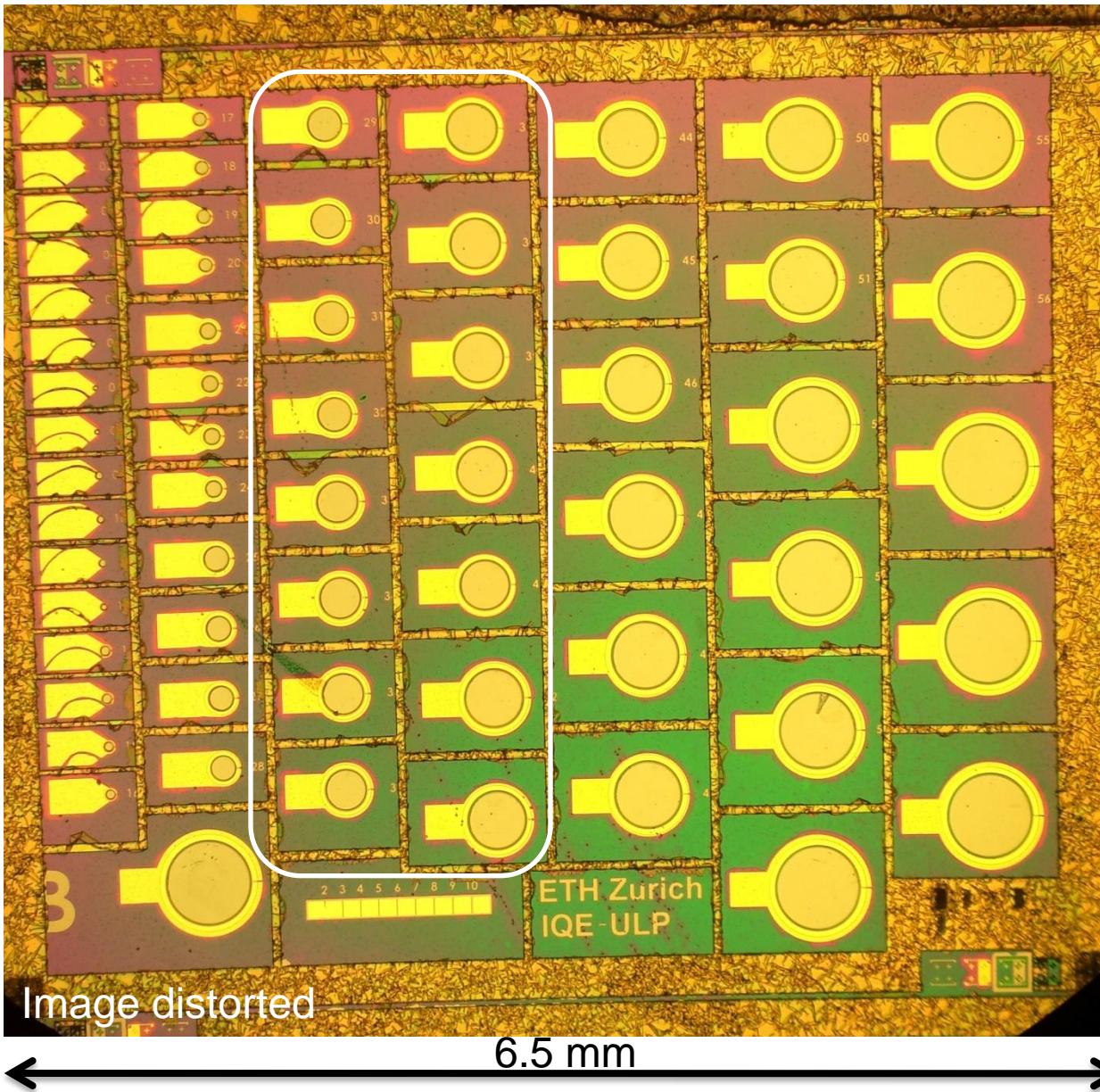


- **Suitable for modelocking**
⇒ no excessive resonances, low dispersion
- **Low-loss, high conductivity p-DBR**
⇒ large aperture possible
⇒ high power achievable
- **Use wafer bonding on CuW wafer**
- **Good electrical contacts**
 - Donut n-contact
 - Small disk p-contact
- **Uniform current injection**
by thick spreading layer (shown in red)
- **Increased gain**
by intermediate DBR
- **AR coating etched for lower resistance**

P. Kreuter et al., *Appl. Phys. B*, **91**, 257, 2008

EP-VECSEL chip

↑
5.5 mm
↓

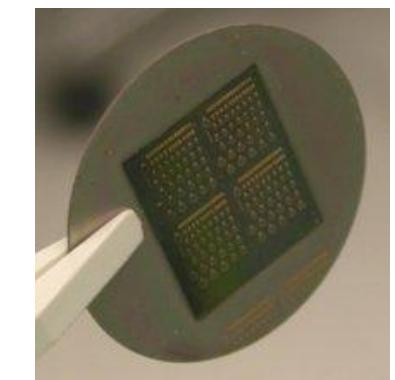


EP-VECSEL target:

Bottom contact
diameter : 50-100 μm

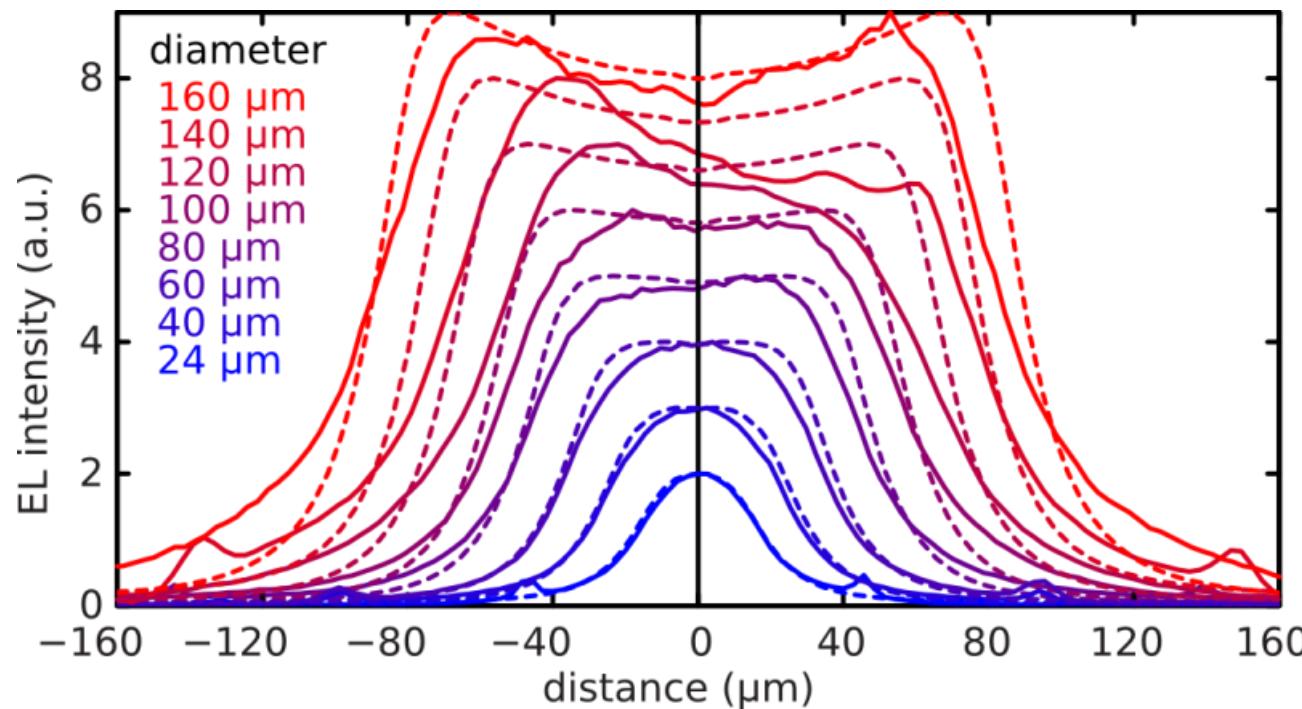
Top ring contact
diameter: 100-300 μm

Larger EP-VECSEL
⇒ multimode output
beam expected

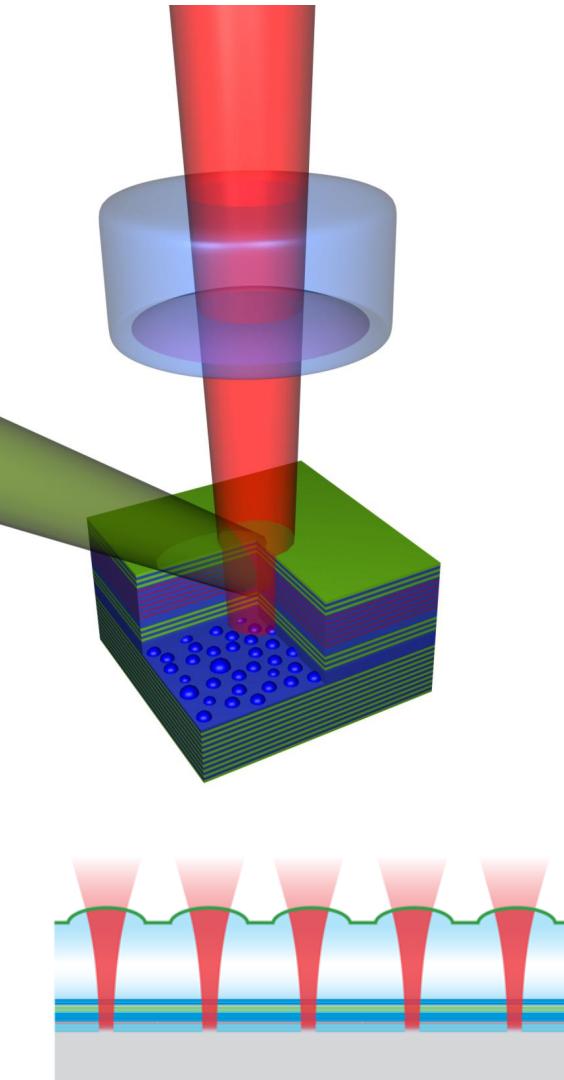


First EP-VECSEL results

- ✓ Growth, processing, and evaluation implemented
- ✓ 60 different EP-VECSEL lasing in cw
- ✓ Output power up to 120 mW (cw) achieved
- ✓ Good homogenous electroluminescence profiles measured for devices up to 100 μm (excellent agreement with our simulations)



Conclusions



Passively modelocked VECSEL with an integrated saturable absorber:

MIXSEL (Modelocked Integrated External-Cavity Surface Emitting Laser)

- modelocking with **6.4 W** was obtained at 2.5 GHz
- modelocking with 200 mW at 10 GHz (not yet optimized)

Next steps

- Optimization dispersion and SESAM recovery time:
 - Reduce pulse duration
- Electrical pumping:
 - Simple, compact, cost-efficient device



European Network of Excellence on
Photonic Integrated Components and Circuits



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Intel Corporation through a university
sponsored research agreement